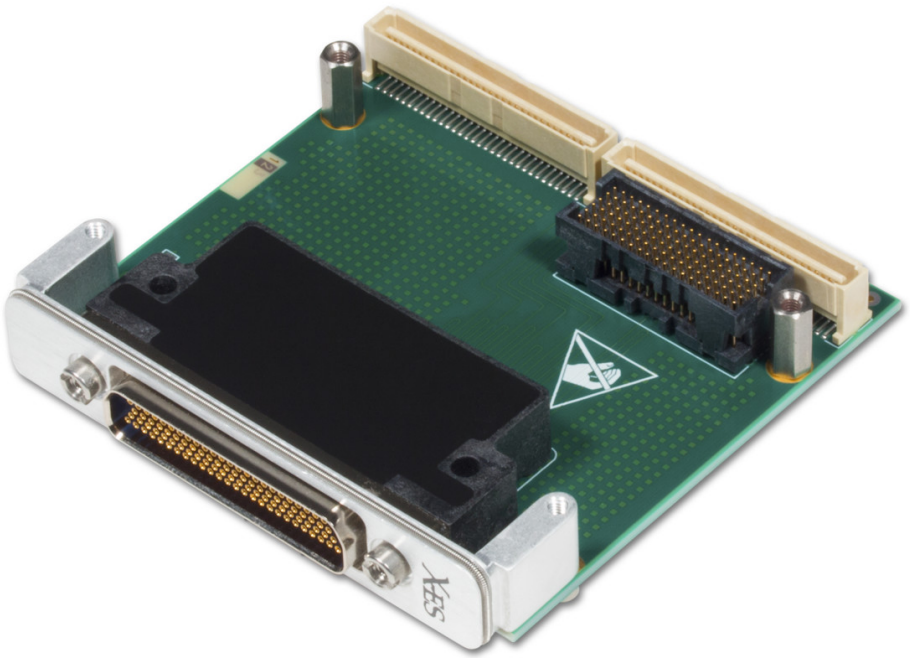
XIt2013

XMC/PMC I/O Breakout Module

- XIM/PIM module
- High-density, rugged Glenair 100-pin connector, part number MWDM2L-100SCBR-.110
- Routes length-matched X12d I/O from P16
- Routes length-matched X8d I/O from P16
- Routes length-matched X38s from P16 or P14 (subset of P64s I/O)
- Compatible with many X-ES RTMs



XIt2013

The XIt2013 is a XIM/PIM module that breaks out P14 and P16 I/O to a general-purpose high-density 100-pin micro-D connector for easy connectivity to other devices. It is intended to mate with a Rear Transition Module (RTM), which routes the XMC/PMC rear I/O from the VPX interface in accordance with ANSI/VITA 46.9 to a XIM site.

The differential X12d and X8d signals are impedance-controlled and length-matched, within each group, from an XMC connector. These create an ideal way to break out high-speed interfaces from an XMC mezzanine card, such as a video interface from a graphics card.

The single-ended X38s signals are also impedance-controlled and length-matched from an XMC connector, which allows connectivity from X38s or X24s. Alternatively, a subset of P64s I/O (based on RTM support) is available.

X-ES Extreme Engineering Solutions

...Always Fast

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I/O Support

- High-density, rugged Glenair 100-pin connector
- Routes length-matched X12d I/O from P16
- Routes length-matched X8d I/O from P16
- Routes length-matched X38s from P16 or P14 (subset of P64s I/O)
- I/O signal pinout mapping table available upon request, contact factory

Physical Characteristics

- XMC/PMC I/O module (XIM/PIM)
- Dimensions: 74 mm x 69 mm

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1
- Conformal coating available as an ordering option

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g²/Hz (maximum), 5 to 2000 Hz	0.04 g²/Hz (maximum), 5 to 2000 Hz	0.1 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing